



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Sectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2015-11-23</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

### Uncertainty Statement

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### Legal Statement

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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### Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KDQJ*HDC3B56	A	SH1A	2015-11-23
Amount	UoM	Unit type	ST ECOPACK Grade	
4.20	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC125)	NAC	NAC		

Package Designator	Size	Nbr of instances	Shape	
WAFER	1.35 - 1.99 - 0.4	10	bulk solder	
Comment	Package: CSPS0.5 4-25 ball 250, MD valid for CP:HDMI2C4-5F2			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KDQ*HDC3856					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	4.200	mg	supplier	die	Silicon (Si)	7440-21-3		3.433	mg	817381	817381
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	4762	4762
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.032	mg	7619	7619
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.005	mg	1190	1190
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.048	mg	11429	11429
Die or Dies				supplier	UBM	Copper (Cu)	7440-50-8		0.022	mg	5238	5238
Die or Dies				supplier	UBM	Titanium (Ti)	7440-32-6		0.004	mg	952	952
Die or Dies				supplier	UBM	Chromium (Cr)	7440-47-3		0.003	mg	714	714
Die or Dies				supplier	UBM	Gold (Au)	7440-57-5		0.005	mg	1190	1190
Die or Dies				supplier	UBM	Nickel (Ni)	7440-02-0		0.021	mg	5000	5000
Die or Dies				supplier	bump	Tin (Sn)	7440-31-5		0.597	mg	142143	142143
Die or Dies				supplier	bump	Silver (Ag)	7440-22-4		0.007	mg	1667	1667
Die or Dies				supplier	bump	Copper (Cu)	7440-50-8		0.003	mg	714	714